

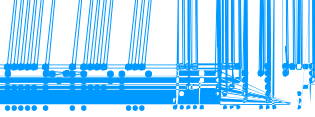
Fine Pitch High Bandwidth Flip Chip Package-on-Package Development

by

**Ming-Che Hsieh, STATS ChipPAC Pte. Ltd.
Stanley Lin, MediaTek, Inc.
Ian Hsu, MediaTek, Inc.
Chi-Yuan Chen, MediaTek, Inc.
NamJu Cho, STATS ChipPAC Korea Ltd.**

**Originally published in the European Microelectronics Packaging Conference,
Warsaw, Poland, Sep 10-13, 2017.
Copyright © 2017.**

**By choosing to view this document, you agree to all provisions of the
copyright laws protecting it.**





EMPC

European Microelectronics
Packaging Conference

September 2017, Warsaw, Poland
www.empc2017.pl



